

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YI-WEI LEE	02/18/2016
ISAAC Y. CHEN	02/18/2016
RECEIVING PARTY DATA	
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State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15076908
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DATE SIGNED:	03/22/2016
Total Attachments: 1	
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RH-1335 V104-015

ASSIGNMENT

WHEREAS, I/we, Yi-Wei Lee and Isaac Y. Chen, have invented certain improvements in:

**“CURRENT REGULATOR CIRCUIT CAPABLE OF REDUCING CURRENT RIPPLE
AND METHOD OF REDUCING CURRENT RIPPLE”**

for which I am/we are about to make application for Letters Patent of the United States; and

WHEREAS, Richtek Technology Corporation, a company having a business address in R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, Yi-Wei Lee and Isaac Y. Chen, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the following execution date, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

I/we further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and I/we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Yi - Wei Lee

(Signature by first inventor/assignor)

2016.2.18

(Date)

Isaac Y. Chen

(Signature by second inventor/assignor)

2016.2.18

(Date)

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